

Title (en)

Suspension for solventless manufacturing of silicon resin bound papers based on stratified silicates

Title (de)

Suspension zur lösemittelfreien Herstellung von siliconharzgebundenen Papieren auf Schichtsilicatbasis

Title (fr)

Suspension pour la fabrication, exempte de solvants, des papiers à base des silicates stratifiés, liés par des résines de type silicone

Publication

EP 0877121 B1 20020703 (DE)

Application

EP 98106666 A 19980411

Priority

DE 19719302 A 19970507

Abstract (en)

[origin: EP0877121A1] A suspension (I) for the solvent free production of silicone resin bound paper consists of: (A) 100 pts.wt. of a layer silicate, (B) 100-10,000 pts.wt. water, (C) 0.1-5 pts.wt. of a silane of formula $(R<1>O)aSiR4-a$ (1), (D) 1-50 pts.wt. of a particulate silicone resin of formula $(R<1>O)bSiRcO(4-bc)/2$ (2), (E) 0.01-20 pts.wt. of a catalyst for the hydrolysis and/or condensation of compounds of formulae (1) and/or (2), and (F) optionally other known additives, whereby for each pt.wt. of (C), 5 pts. wt. (D) are present. In the formulae, R = 1-20C hydrocarbon; $R<1> = 1-10C$ alkyl, aryl, alkylaryl or H; a = 1-3; b = 0-0.5; and c = 0.7 - 1.3 Also claimed is the production of the suspension (I) by mixing (A), (B) and (C) for at least one minute followed by the addition of (D).

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